

Title (en)  
SEISMIC DISSIPATION MODULE MADE UP OF COMPRESSION-RESISTANT SPHERES IMMERSED IN A VARIABLE LOW DENSITY MATERIAL

Title (de)  
SEISMISCHES ABLEITUNGSMODUL AUS EIN MATERIAL VON GERINGER DICHT EINGETAUCHTEN KOMPRESSIONSBESTÄNDIGEN KUGELN

Title (fr)  
MODULE DE DISSIPATION SISMIQUE CONSTITUÉ DE SPHÈRES RÉSISTANT À LA COMPRESSION IMMERGÉES DANS UN MATÉRIAU DE FAIBLE DENSITÉ VARIABLE

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Application  
**EP 12790430 A 20121119**

Priority  
• IT MC20110066 A 20111121  
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Abstract (en)  
[origin: WO2013075814A1] The present invention concerns the industry for making seismic isolators, namely devices used for isolating the load-bearing structure of buildings from the effects of an earthquake and consists of a seismic dissipation and isolation panel or module (1) made up of compression-resistant spheres (2), made of sintered alumina, bound by variable low density substances, polyurethane foams or polystyrene or other similar material (3), to be used in new buildings by placing it between a reinforced concrete bed (4) to be made on the ground (5) and the foundation structures (6) of the building (7), so that, in the event of an earthquake, there can be movements of the building independent from those of the ground on which it is built, so absorbing and isolating the seismic wave and therefore reducing the effects on the structures until, in theory, they cancel them.

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